

WAFER PROCESSING METHOD

ABSTRACT OF THE DISCLOSURE

A processing method for a wafer having a chamfered portion at a peripheral edge includes a holding step of holding the wafer by a holding table, and a chamfer removing step of rotating the holding table while causing a first cutting blade to cut into the peripheral edge of the wafer while supplying a cutting liquid from a first cutting liquid supply nozzle to cut the peripheral edge of the wafer. In the chamfer removing step, a second cutting unit is positioned at a position adjacent to the first cutting unit at such a height that a second cutting blade does not make contact with the wafer and on the side of the center of the wafer as compared to the first cutting unit, and the cutting liquid is supplied from a second cutting liquid supply nozzle.

[Fig. 7]